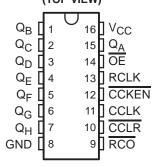
SCLS039F - DECEMBER 1982 - REVISED SEPTEMBER 2003

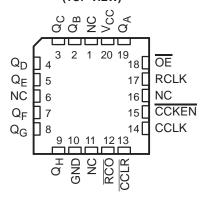
- 2-V to 6-V V_{CC} Operation
- High-Current 3-State Parallel Register
 Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns

SN54HC590A . . . J OR W PACKAGE SN74HC590A . . . D, DW, OR N PACKAGE (TOP VIEW)



- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- 8-Bit Counter With Register
- Counter Has Direct Clear

SN54HC590A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'HC590A devices contain an 8-bit binary counter that feeds an 8-bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register. The binary counter features direct clear (CCLR) and count-enable (CCKEN) inputs. A ripple-carry output (RCO) is provided for cascading. Expansion is accomplished easily for two stages by connecting RCO of the first stage to CCKEN of the second stage. Cascading for larger count chains can be accomplished by connecting RCO of each stage to the counter clock (CCLK) input of the following stage.

CCLK and the register clock (RCLK) inputs are positive-edge triggered. If both clocks are connected together, the counter state always is one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

ORDERING INFORMATION

TA	PACI	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC590AN	SN74HC590AN
		Tube of 40	SN74HC590AD	
4000 1- 0500	SOIC - D	Reel of 2500	SN74HC590ADR	HC590A
-40°C to 85°C		Reel of 250	SN74HC590ADT	
	0010 011	Tube of 40	SN74HC590ADW	1105004
	SOIC - DW	Reel of 2000	SN74HC590ADWR	HC590A
	CDIP – J	Tube of 25	SNJ54HC590AJ	SNJ54HC590AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC590AW	SNJ54HC590AW
	LCCC - FK	Tube of 55	SNJ54HC590AFK	SNJ54HC590AFK

T Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



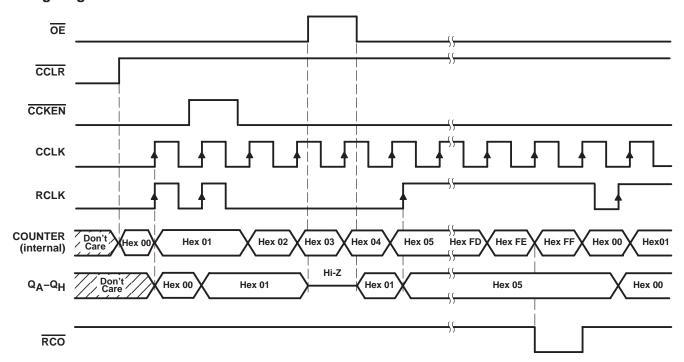
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC590A, SN74HC590A 8-BIT BINARY COUNTERS WITH 3-STATE OUTPUT REGISTERS

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timing diagram

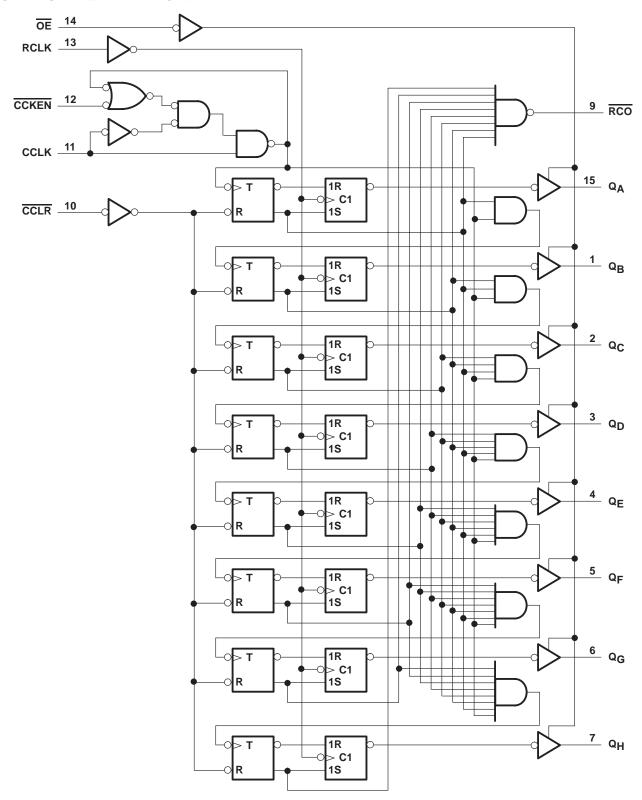


TIMING SEQUENCE

- 1. Clear Counter (asynchronous).
- 2. Count up: 0x01. Store 0x00 in register.
- 3. Inhibit counter clock (CCKEN = HIGH). Store 0x01 in register.
- 4. Count 0x02, 0x03.
- 5. 3-state the outputs
- 6. Count up: 0x04
- 7. Enable outputs.
- 8. Continue up: 0x059. Store 0x05 in register.
- 10. Continue counting: 0x06...0xFD, 0xFE, 0xFF, 0x00, etc.
- 11. Store 0x00 in register.



logic diagram (positive logic)



Pin numbers shown are for the D, DW, J, N, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ _{JA} (see Note 2)	: D package	
	DW package	57°C/W
	N package	67°C/W
Storage temperature range, T _{sto}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	54HC59	0A	SN	74HC590)A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
V_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		VCC = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
t _t ‡	Input transition (rise and fall) time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

[‡] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CCLK and RCLK inputs are not ensured while in the shift, count, or toggle operating modes.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		CONDITIONS	.,	Т	A = 25°C	;	SN54H	C590A	SN74H	C590A	
PARAMETER	TEST	CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
Voн	VI = VIH or VIL	\overline{RCO} , $I_{OH} = -4 \text{ mA}$	45.7	3.98	4.3		3.7		3.84		V
		$Q_A - Q_H$, $I_{OH} = -6$ mA	4.5 V	3.98	4.3		3.7		3.84		
		\overline{RCO} , $I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
		$Q_A - Q_H$, $I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL	RCO, I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	V
		Q_A-Q_H , $I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		\overline{RCO} , $I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
		Q_A-Q_H , $I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	VI = VCC or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

SN54HC590A, SN74HC590A 8-BIT BINARY COUNTERS WITH 3-STATE OUTPUT REGISTERS SCLS039F - DECEMBER 1982 - REVISED SEPTEMBER 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			.,	T _A = 1	25°C	SN54H	C590A	SN74H	C590A	
			VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		4		2.5		3.2	
fclock	Clock frequency		4.5 V		20		13		16	MHz
			6 V		24		16		19	
			2 V	125		200		155		
		CCLK or RCLK high or low	4.5 V	25		38		31		
	Dodge deserve		6 V	21		32		26		
t _W	Pulse duration		2 V	100		150		125		ns
		CCLR low	4.5 V	20		30		25		
			6 V	17		26		21		
			2 V	100		150		125		
		CCKEN low before CCLK↑	4.5 V	20		30		25		
			6 V	17		26		21		
			2 V	100		150		125		
t _{su}	Setup time	CCLR high (inactive) before CCLK↑	4.5 V	20		30		25		ns
			6 V	17		26		21		
			2 V	100		150		125		
		CCLK↑ before RCLK↑†	4.5 V	20		30		25		
			6 V	17		26		21		
	<u> </u>		2 V	50		75		60		
th	Hold time	CCKEN low after CCLK↑	4.5 V	10		15		12		ns
			6 V	9		13		11		

[†] This setup time ensures that the register gets stable data from the counter outputs. The clocks may be tied together, in which case the register is one clock pulse behind the counter.



switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

					SN	54HC590	0A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	T,	ղ = 25°C	;		MAY	UNIT
	(1141 01)	(0011 01)		MIN	TYP	MAX	MIN	MAX	
			2 V	4	8		2.5		
f _{max}			4.5 V	20	35		13		MHz
			6 V	24	40		16		
			2 V		80	150		225	
^t pd	CCLK↑	RCO	4.5 V		20	31		45	ns
'			6 V		15	26		38	
			2 V		70	130		195	
^t PLH	CCLR↓	RCO	4.5 V		18	28		39	ns
			6 V		14	23		33	
			2 V		70	140		210	
t _{pd}	RCLK↑	Q	4.5 V		18	31		42	ns
			6 V		14	25		36	
			2 V		80	125		185	
t _{en}	ŌĒ↓	Q	4.5 V		20	30		37	ns
			6 V		15	28		31	
			2 V		80	125		185	
^t dis	ŌĒ↑	Q	4.5 V		20	30		37	ns
4.0			6 V		15	28		31	
			2 V		38	75		110	
		RCO	4.5 V		8	15		22	
*			6 V		6	13		19	
t _t *			2 V		38	60		90	ns
		Q	4.5 V		8	12		18	
			6 V		6	10		15	

^{*} This parameter is not production tested for the SN54HC590A.

SN54HC590A, SN74HC590A 8-BIT BINARY COUNTERS WITH 3-STATE OUTPUT REGISTERS SCLS039F - DECEMBER 1982 - REVISED SEPTEMBER 2003

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

					SN	74HC59	0A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	T,	չ = 25°C	;	BAINI	BAAV	UNIT
	(1141 01)	(0011 01)		MIN	TYP	MAX	MIN	33 165 33 28 175 35 30 155 31 26 155 31 26 95 19	
			2 V	4	8		3.2		
f _{max}			4.5 V	20	35		16		MHz
			6 V	24	40		19		
			2 V		80	150		190	
t _{pd}	CCLK↑	RCO	4.5 V		20	30		38	ns
·			6 V		15	26		33	
			2 V		70	130		165	
t _{PLH}	CCLR↓	RCO	4.5 V		18	26		33	ns
			6 V		14	22		28	
			2 V		70	140		175	
t _{pd}	RCLK↑	Q	4.5 V		18	28		35	ns
·			6 V		14	24		30	
			2 V		80	125		155	
t _{en}	ŌE↓	Q	4.5 V		20	25		31	ns
			6 V		15	21		26	
			2 V		80	125		155	
^t dis	OE↑	Q	4.5 V		20	25		31	ns
			6 V		15	21		26	
			2 V		38	75		95	
		RCO	4.5 V		8	15		19	
			6 V		6	13		16	ns
t _t			2 V		38	60		75	110
		Q	4.5 V		8	12		15	
			6 V		6	10		13	



switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

					SN	54HC59	0A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	TA	√ = 25°C	;	MINI	MAY	UNIT
	(1141 01)	(0011 01)		MIN	TYP	MAX	MIN	MAX	
			2 V		100	300		447	
^t pd	RCLK↑	Q	4.5 V		24	60		90	ns
·			6 V		20	51		77	
			2 V		90	200		300	
t _{en}	ŌĒ	Q	4.5 V		23	40		60	ns
			6 V		19	34		51	
			2 V		45	210		315	
t _t *		Q	4.5 V		17	42		63	ns
			6 V		13	36		53	

^{*} This parameter is not production tested for the SN54HC590A.

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

					SN	74HC59	0A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC	TA	\ = 25°C	;	MIN	BAAV	UNIT
	(51)	(0011 01)		MIN	TYP	MAX	IVIIIN	MAX	
			2 V		100	300		380	
^t pd	RCLK↑	Q	4.5 V		24	60		76	ns
·			6 V		20	51		65	
			2 V		90	200		250	
t _{en}	ŌĒ	Q	4.5 V		23	40		50	ns
			6 V		19	34		43	
			2 V		45	210		265	
t _t		Q	4.5 V		17	42		53	ns
			6 V		13	36		45	

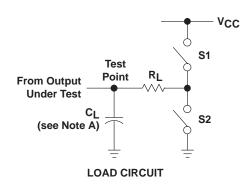
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	250	pF

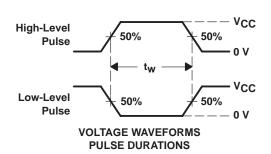


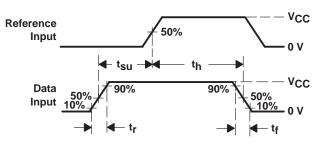
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PARAMETER MEASUREMENT INFORMATION

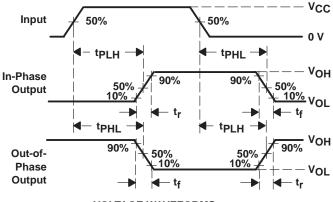


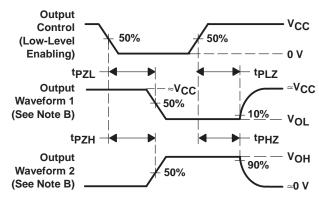
PARAI	METER	RL	CL	S1	S2
	tPZH	1 k Ω	50 pF or	Open	Closed
ten	tPZL	1 K22	150 pF	Closed	Open
	tPHZ	410		Open	Closed
^t dis	tPLZ	1 k Ω	50 pF	Closed	Open
t _{pd} or	t _t		50 pF or 150 pF	Open	Open





VOLTAGE WAVEFORMS SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 6 ns, t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







31-May-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
5962-89603012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 89603012A SNJ54HC 590AFK	Sample
5962-8960301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8960301EA SNJ54HC590AJ	Sample
5962-8960301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8960301FA SNJ54HC590AW	Sample
SN54HC590AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC590AJ	Sample
SN74HC590AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sample
SN74HC590ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADTE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85		Sampl
SN74HC590ADTG4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85		Sampl
SN74HC590ADW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Sampl
SN74HC590ADWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Samp
SN74HC590ADWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC590A	Samp
SN74HC590ADWRG4	ACTIVE	SOIC	DW	16		TBD	Call TI	Call TI	-40 to 85		Sampl



PACKAGE OPTION ADDENDUM

31-May-2014

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC590AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC590AN	Samples
SN74HC590AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	-40 to 85		
SN74HC590ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC590AN	Samples
SNJ54HC590AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 89603012A SNJ54HC 590AFK	Samples
SNJ54HC590AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8960301EA SNJ54HC590AJ	Samples
SNJ54HC590AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8960301FA SNJ54HC590AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

31-May-2014

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC590A, SN74HC590A:

Catalog: SN74HC590A

Military: SN54HC590A

NOTE: Qualified Version Definitions:

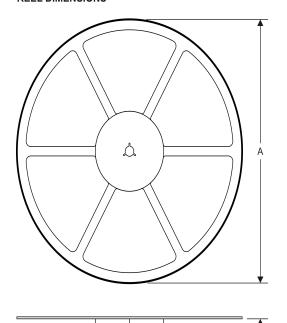
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

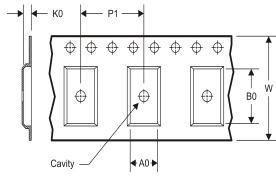
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS







A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

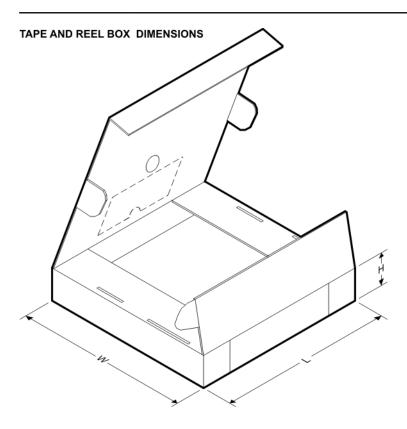
TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC590ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC590ADWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC590ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC590ADWR	SOIC	DW	16	2000	367.0	367.0	38.0

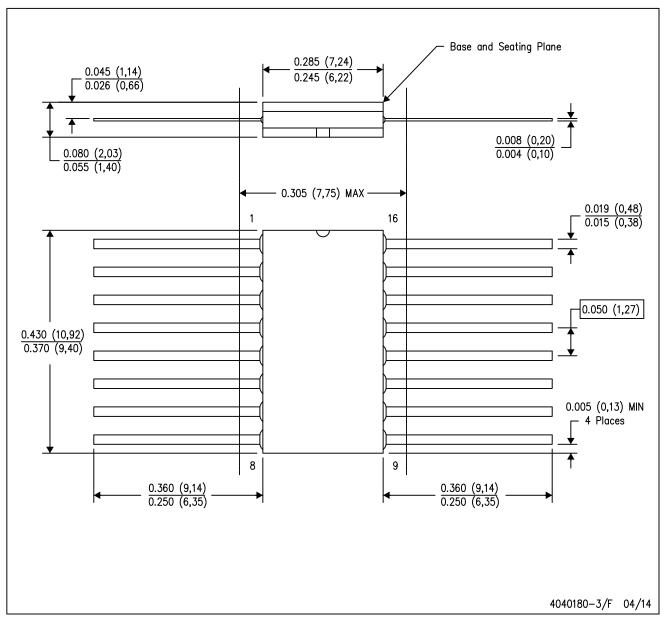
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE

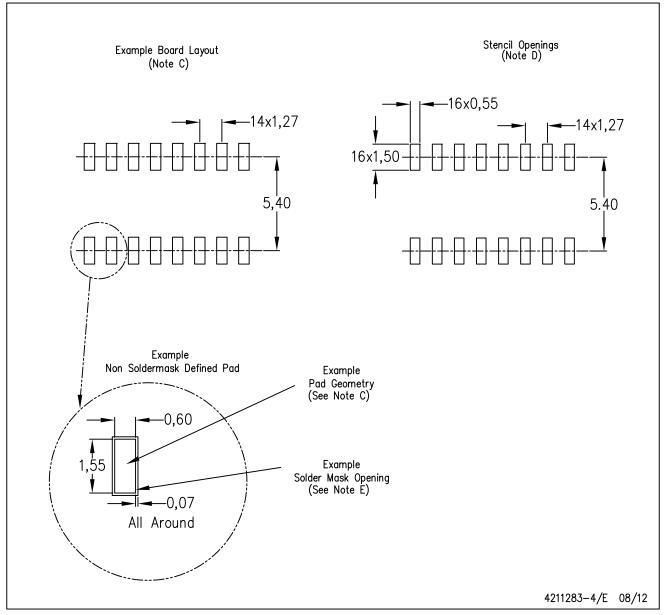


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

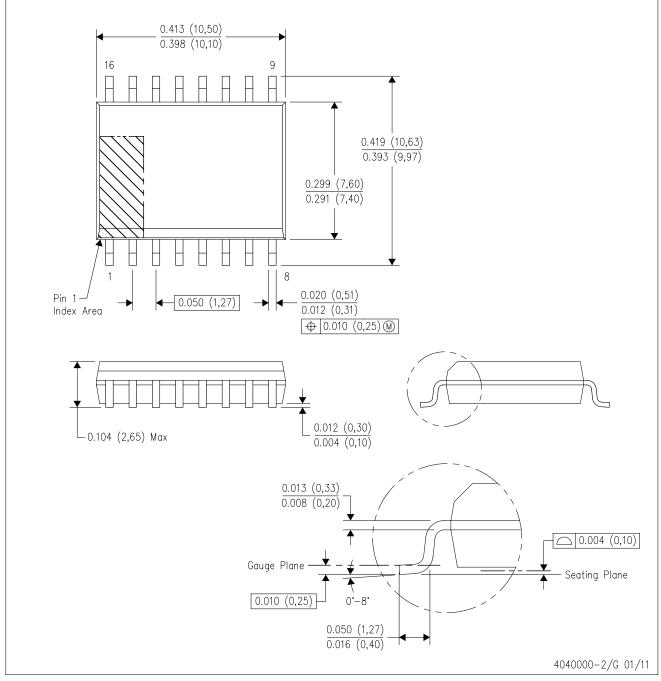


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



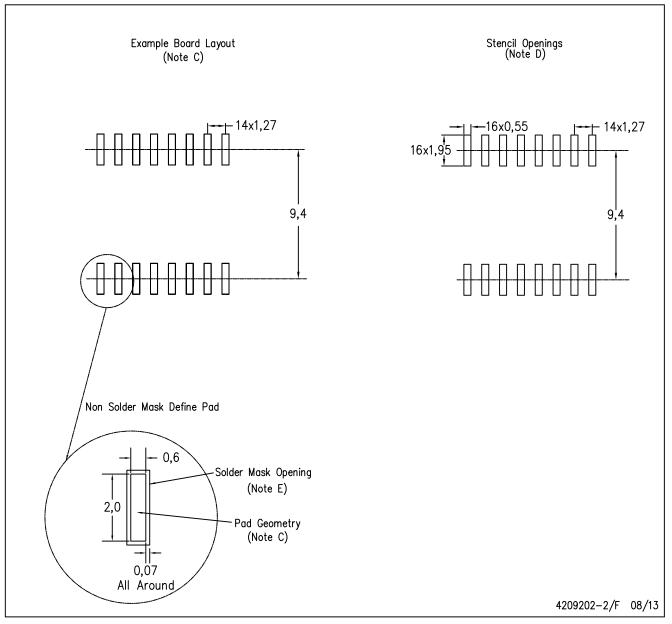
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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